

# Nordic Semiconductor RoHS Statement

Document ID: HSM\_003 Rev. 1.2



## Scope

This declaration is applicable to all integrated circuits and System-in-Package modules, collectively "Products", supplied by Nordic Semiconductor.

It takes precedence over the RoHS- and REACH statement portions of Product Specifications published before March 2019.

## Substance Restrictions

Annex II of EU RoHS 2 Directive 2011/65/EU and its amending Directive (EU) 2015/863, hereinafter collectively referred to as "EU RoHS 2", restrict the following substances with corresponding threshold limits:

| <i>Restricted Substance</i>             | <i>Threshold limit</i> |
|-----------------------------------------|------------------------|
| Cadmium (Cd)                            | 0.01%                  |
| Mercury (Hg)                            | 0.1%                   |
| Lead (Pb)                               | 0.1%                   |
| Hexavalent Chromium (Cr <sup>6+</sup> ) | 0.1%                   |
| Polybrominated biphenyls (PBB)          | 0.1%                   |
| Polybrominated diphenyl ethers (PBDE)   | 0.1%                   |
| Bis (2-ethylhexyl) phthalate (DEHP)     | 0.1%                   |
| Butyl benzyl phthalate (BBP)            | 0.1%                   |
| Dibutyl phthalate (DBP)                 | 0.1%                   |
| Diisobutyl phthalate (DIBP)             | 0.1%                   |

All Nordic Semiconductor Products are EU RoHS 2 compliant.

The mentioned substances may in certain applications be employed in ratios above the threshold limits. Applicable exemptions are listed in Annex III of 2011/65/EU.

Certain Nordic Semiconductor Products exceed the default limit for Lead and depend on exemption 7(c)-I to meet compliance:

7(c)-I *Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound*

Samples of all Products are periodically sent for laboratory testing to verify its compliance to RoHS substances restrictions. A copy of the Hazardous Substance Report (HSR) for each product is available on the Nordic Semiconductor [Website](#).

## Homogeneous Materials

Test reports for each homogenous material from suppliers are collected and reviewed by Nordic Semiconductor according to the requirements described in IEC 63000:2016 and EN50581:2012. These reports can be made available upon request.

Information on hazardous substance content by homogeneous materials are found in Material Composition Reports (MCR) which are available on the Nordic Semiconductor [Website](#).

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### Labelling

Products that meet all substance restrictions for each homogenous material and that satisfy EU RoHS 2 without use of any provision for exemption exhibit a Pb-free symbol in the labels:



*Pb-free symbol*

### China RoHS 2

The Administrative Measures for the Restriction of the Use of Hazardous Substances in Electrical and Electronic Products, known as China RoHS 2, mandates end-product specific marking for six hazardous substances: Lead (Pb), Mercury (Hg), Cadmium (Cd), Hexavalent Chromium (Cr<sup>6+</sup>), PBB, and PBDE.

Threshold limits are the same as with EU RoHS 2. Nordic Semiconductor Products that are China RoHS compliant can therefore physically be identified by their Pb-free logo.

### Authorized signatory for Nordic Semiconductor:

A handwritten signature in black ink, appearing to read 'Ebbe Rømcke', written over a horizontal line.

Ebbe Rømcke  
Quality Director  
Date: March 25<sup>th</sup>, 2019

### Contact information:

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